



PROCESS APPLICATION GUIDE

TIN PROCESS SELECTOR GUIDE

PLEASE NOTE: This document is for guidance only.
Please refer to the appropriate Technical Data Sheet for additional information.

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TIN PLATING PROCESS SELECTOR GUIDE

Process	Deposit Appearance	Applications/ Market	Electrolyte	Current Density Range	Comments
Technibrite HT 1000	Bright	Rack and barrel plating	Sulfate	0.3 - 10 ASD 3 - 100 ASF	Full bright deposits over a wide CD range for rack and barrel applications. Nonyl phenol ethoxylate (NPE) free
Technistan TP-5000	Matte/Satin	High speed reel-to-reel for tin reflow on copper strip	Sulfate	5 - 40 ASD 50 - 400 ASF	Satin finish pure tin high speed process. Deposit morphology is specifically suitable for in-line reflow applications. Must be run at 95-131°F/35-55°C. Has exceptional throwing power for a high speed process.
Technistan JM 7000	Matte	High speed reel-to-reel	Sulfate	5 - 40 ASD 50 - 400 ASF	Satin finish resists discoloration when exposed to high temperature reflow. Excellent solderability. Good throwing power/coverage. Recommended as undercoat for duplex tin plating systems.
Technistan TP-W	Matte	Industrial - wire	Sulfate	10 - 80 ASD 100 - 800 ASF	High speed matte pure tin wire plating process based on sulfuric acid technology. Offers significant cost advantages to MSA systems.
Techni NF JB 3000 / Techni NF JB 3000 NS	Bright	Reel-to-reel	MSA	5 - 30 ASD 50 - 300 ASF	Bright, whisker resistant pure tin based on MSA. Satisfies all requirements of JEDEC JESD 201. Can be formulated for high and medium speed applications.
Techni NF JM 6000 LS	Matte	Rack and barrel plating	MSA	0.1 - 4 ASD 1 - 40 ASF	Matte whisker resistant deposit based on MSA. Requires solution heating to 115°F/46°C.
Techni NF JM 8000	Matte	High speed reel-to-reel connector and semiconductor components	MSA	5 - 100 ASD 50 - 1000 ASF	Matte tin deposits from an MSA electrolyte. Recommended for whisker resistant and reflow applications.
Ceramistan 1031	Matte	SBE applications (chip capacitors/ chip resistors)	MSA	0.05 - 2 ASD 0.5 - 20 ASF	Matte tin plating process for standard chip capacitor/chip resistor plating applications. Suitable for barrel plating or SBE equipment. Excellent whisker resistance and solderability